# 150V, 75A, 13.6mΩ N-channel Power SGT MOSFET

### JMSL1509PG

#### **Features**

- $\bullet \quad \text{Excellent $R_{\text{DS(ON)}}$ and Low Gate Charge}$
- 100% UIS Tested
- 100% ΔVds Tested
- Halogen-free; RoHS-compliant

### **Applications**

- Load Switch
- PWM Application
- Power Management

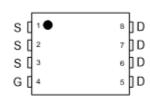
### **Product Summary**

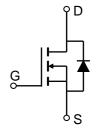
Parameters	Value	Unit
$V_{DSS}$	150	V
$V_{GS(th)\_Typ}$	2.1	V
$I_D(@V_{GS}=10V)$	75	Α
$R_{DS(ON)\_Typ}(@V_{GS}=10V$	10.2	mΩ
$R_{DS(ON)\_Typ}(@V_{GS}=4.5V$	13.6	mΩ











PDFN5X6-8L

**Pin Assignment** 

**Schematic Diagram** 

### **Ordering Information**

	Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
I	JMSL1509PG	SL1509P	1	Tape&Reel	PDFN5x6-8L	5000	50000

# **Absolute Maximum Ratings** (@ $T_C = 25$ °C unless otherwise specified)

Symbol	Parameter		Value	Unit
$V_{DS}$	Drain-to-Source Voltage		150	V
$V_{GS}$	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	$T_C = 25^{\circ}C$	75	Λ
I <sub>D</sub>		$T_C = 100$ °C	47	А
I <sub>DM</sub>	Pulsed Drain Current (1)		Refer to Fig.4	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (2)		389	mJ
P <sub>D</sub>	Power Dissipation	$T_C = 25^{\circ}C$	156	W
		$T_C = 100$ °C	63	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
$T_{J}, T_{STG}$	Junction & Storage Temperature Range		-55 to 150	°C

### **Thermal Characteristics**

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	40	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.8	C/VV



### **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

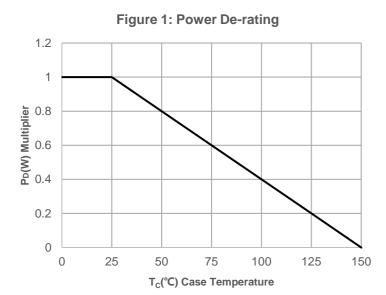
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 120V, V_{GS} = 0V$	-	-	1.0	μА
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics	•				
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.5	2.1	2.7	V
D	Static Drain-Source ON-Resistance <sup>(4)</sup>	$V_{GS} = 10V, I_D = 20A$	-	10.2	13.3	mΩ
$R_{DS(ON)}$	Static Drain-Source ON-Resistance	$V_{GS} = 4.5V, I_D = 15A$	-	13.6	17.6	mΩ
Dynami	c Characteristics					
$R_g$	Gate Resistance	f = 1MHz	-	1.2	-	Ω
C <sub>iss</sub>	Input Capacitance		2030	2842	3837	pF
C <sub>oss</sub>	Output Capacitance	$V_{GS} = 0V, V_{DS} = 75V,$ f = 1MHz	240	336	453	pF
$C_{rss}$	Reverse Transfer Capacitance	1 - 11/11/2	14	19	26	pF
Q <sub>g</sub>	Total Gate Charge	V 0 40V	30	42	57	nC
$Q_{gs}$	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 75V, I_{D} = 15A$	8	11	15	nC
$Q_{gd}$	Gate Drain("Miller") Charge	= V <sub>DS</sub> = 75V, I <sub>D</sub> = 15A	-	7.7	-	nC
<u>Switchi</u>	ng Characteristics	1		1	ı	ı
t <sub>d(on)</sub>	Turn-On DelayTime		-	26	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 75V$	-	89	-	ns
$t_{\text{d(off)}}$	Turn-Off DelayTime	$I_D = 20A$ , $R_{GEN} = 3\Omega$	-	26	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	16	-	ns
Body D	iode Characteristics			ı	ı	ı
I <sub>S</sub>	Maximum Continuous Body Diode Forward Current		-	-	75	Α
$I_{SM}$	Maximum Pulsed Body Diode Forward Cur	rent	-	-	298	Α
$V_{\text{SD}}$	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 20A$	-		1.2	V
trr	Body Diode Reverse Recovery Time	I <sub>F</sub> = 20A, di/dt = 100A/us	60	84	113	ns
Qrr	Body Diode Reverse Recovery Charge	IF = 20A, al/at = 100A/as	-	233	-	nC

Notes:

- 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
- $2.~E_{AS}~condition:~Starting~T_J=25C,~V_{DD}=75V,~V_{GS}=10V,~R_G=25ohm,~L=3mH,~I_{AS}=16.1A,~V_{DD}=0V~during~time~in~avalanche.$
- 3.  $R_{\theta JA}$  is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB.
- 4. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  0.5%.



# **Typical Performance Characteristics**



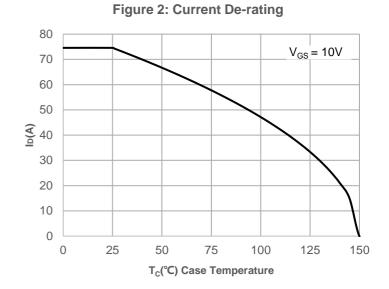
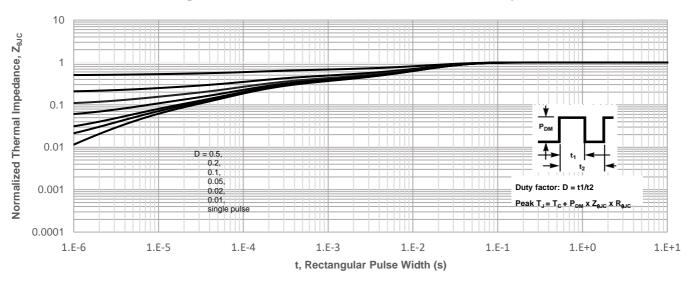
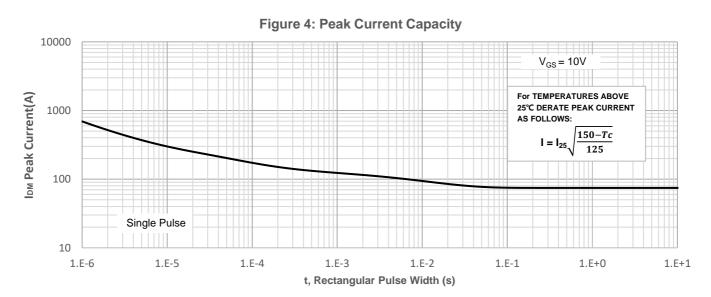


Figure 3: Normalized Maximum Transient Thermal Impedance

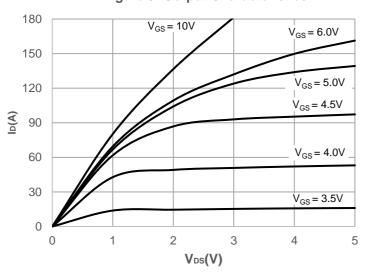






# **Typical Performance Characteristics**

Figure 5: Output Characteristics



**Figure 6: Typical Transfer Characteristics** 

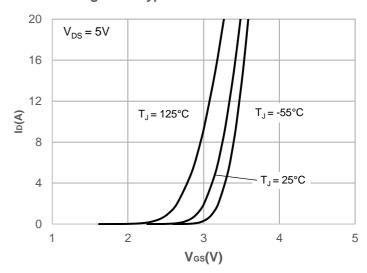
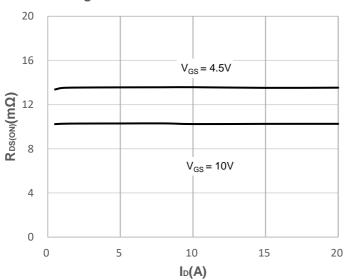
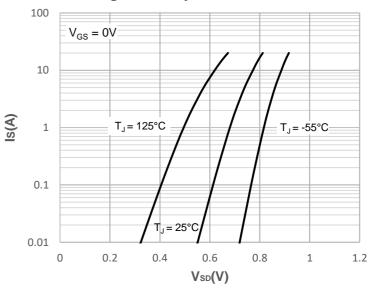


Figure 7: On-resistance vs. Drain Current



**Figure 8: Body Diode Characteristics** 



**Figure 9: Gate Charge Characteristics** 

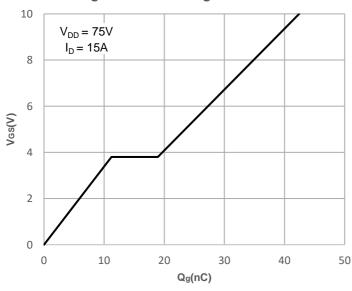
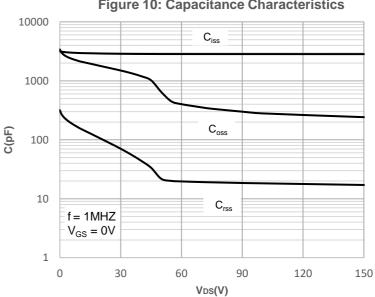


Figure 10: Capacitance Characteristics





# **Typical Performance Characteristics**

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

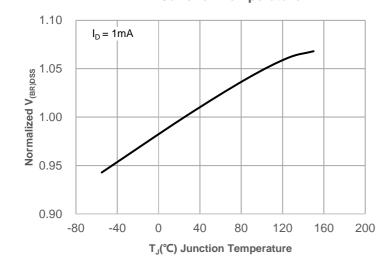


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

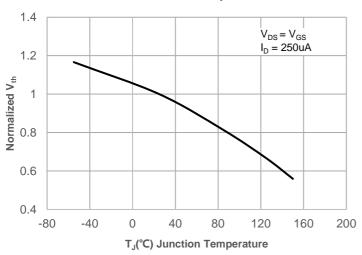


Figure 15: Maximum Safe Operating Area

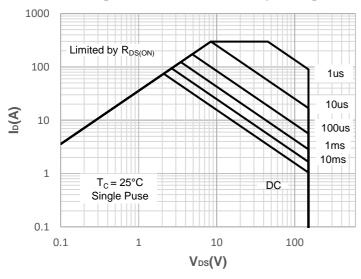
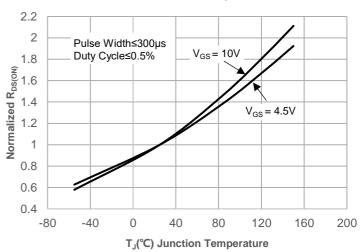
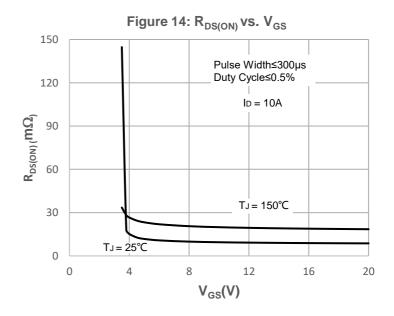


Figure 12: Normalized on Resistance vs. Junction Temperature







# **Test Circuit**

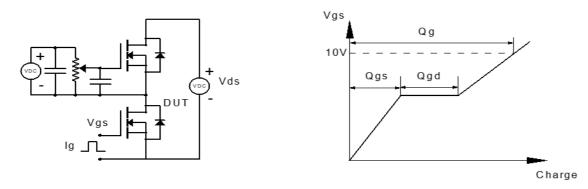


Figure 1: Gate Charge Test Circuit & Waveform

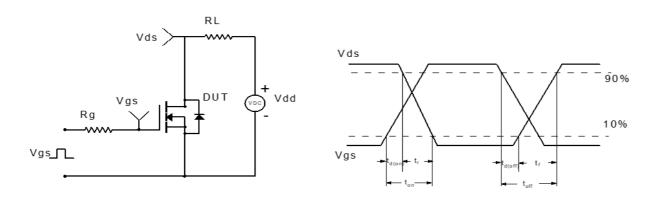


Figure 2: Resistive Switching Test Circuit & Waveform

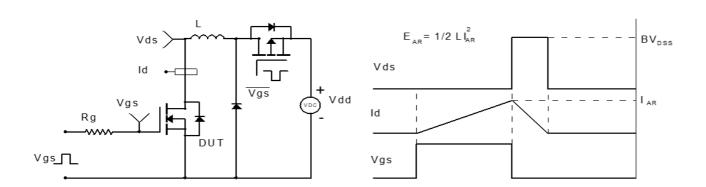


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

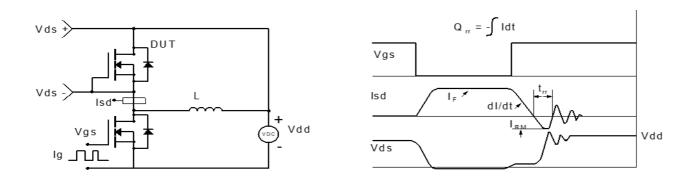
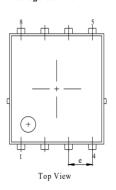


Figure 4: Diode Recovery Test Circuit & Waveform

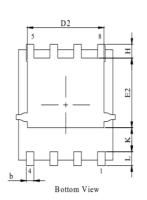


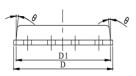
## Package Mechanical Data(PDFN5X6-8L)

#### Package Outline









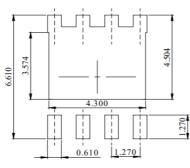
Front View

NOTES:

- Dimension and tolerance per ASME Y14.5M, 1994. All dimensions in millimeter (angle in degree). Dimensions D1 and E1 do not include mold flash protrusions or gate burrs.

D.T.V	MILLIMETER				
DIM.	MIN.	NOM.	MAX.		
A	0. 9	1	1. 15		
b	0.31	0. 41	0. 51		
С	0. 24	0. 32	0. 4		
D	5	5. 2	5. 4		
D1	4. 95	5. 05	5. 15		
<b>D</b> 2	4	4. 1	4. 2		
E	6.05	6. 15	6. 25		
E1	5. 5	5. 6	5. 7		
E2	3. 42	3, 53	3. 63		
е	1. 27BSC				
Н	0.6	0.7	0.8		
L	0.5	0.7	0.8		
K	1.23 REF				
0			10		

#### Recommended Soldering Footprint



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